Erratum to: Structural and Thermoelectric Properties of Nanocrystalline Bismuth Telluride Thin Films Under Compressive and Tensile Strain

K. KUSAGAYA,
^ H. HAGINO,
^ S. TANAKA,
^ K. MIYAZAKI,
^ and M. TAKASHIRI
^1,4

1.—Department of Materials Science, Tokai University, 4-1-1 Kitakaname, Hiratsuka, Kanagawa 259-1292, Japan. 2.—Department of Mechanical and Control Engineering, Kyushu Institute of Technology, 1-1 Sensui, Tobata-ku, Kitakyushu 804-8550, Japan. 3.—Department of Mechanical Engineering, College of Engineering, Nihon University, 1 Nakagawara, Tokusada, Tamuramachi, Koriyama, Fukushima 963-8642, Japan. 4.—e-mail: takashiri@tokai-u.jp

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Following are corrections to the original article:

- 1. Figure 5 is corrected as shown in this erratum.
- 2. Due to this change, the relationship between the direction of strain and the in-plane thermoelectric properties becomes opposite trends, presenting in section of Abstract, Thermoelectric Properties of Strained Bismuth Telluride Thin Films, and Conclusion.
- 3. The section of Thermoelectric Properties of Strained Bismuth Telluride Thin Films, first

paragraph: "One possible explanation of the increase in electrical conductivity...."should be deleted. In addition, reference 28 should be also deleted.

- 4. The section of Thermoelectric Properties of Strained Bismuth Telluride Thin Films, third paragraph: "Compared with previously....indicative of trends opposite to those observed...." should be "Compared with previously....indicative of similar trends to those observed...."
- 5. The section of Thermoelectric Properties of Strained Bismuth Telluride Thin Films, of third paragraph from "The reason our results differ from...."to the end of the paragraph should be deleted.

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Fig. 5. (a) Electrical conductivity, (b) Seebeck coefficient, and (c) power factor of bismuth telluride thin films as a function of applied strain.